



InterPACK 2024

International Technical Conference and Exhibition on Packaging and Integration of Electronic and Photonic Microsystems

CALL FOR PAPERS

Special Issue – InterPACK 2024 of ASME Journal of Electronic Packaging

InterPACK is a premier international forum for exchanging state-of-the-art knowledge in research, development, manufacturing, and electronic packaging applications and heterogeneous integration. It is also the flagship conference of the ASME Electronic and Photonic Packaging Division (EPPD). The Journal of Electronic Packaging (JEP) publishes papers that use experimental and theoretical methods, approaches, and techniques to address and solve various mechanical, materials, thermal, and reliability problems encountered in the analysis, design, manufacturing, testing, and operation of electronic and photonics components, devices, and systems.

Authors are invited to submit their manuscripts revised from their original conference papers to be considered for the Special Issue. These papers will be reviewed by the AE/GE and go through the normal JEP review process. Presentation-only contributors are also invited to develop full-length manuscripts and submit them for review. This InterPACK Special Issue aims to publish outstanding papers with diverse scientific works representing all tracks of InterPACK2024.

Submission Instructions

Should you have any questions, please get in touch with Saket Karajgikar at skarajgikar@nvidia.com.

1. The SI is targeted to publish honorary-quality papers with InterPACK2024 flavor, but it's not equivalent to conference proceedings.
2. The submission should be directly revised from the InterPACK2024 paper or technical presentation. Please include the original InterPACK paper in the appendix of your submission to this SI through the [ASME Journal Tool](#).

Topic Areas

The scope of this issue includes but not limited to:

- Heterogeneous Integration
- Data Centers and Modular Edge Systems
- Electronics Packaging
- Power/RF Electronics and Photonics
- Multiscale Thermal Transport and Energy Storage
- Flexible, Wearable, and Printed Electronics
- Transportation Systems
- AI/ML

Publication Dates

2025	
Feb 28	Paper Submission Deadline
2025	
Jun 30	Initial Review Completed
2025	
Dec 01	Publication Date

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